



Gp/2827

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: HUEMOELLER ET AL. / DOCKET NO.: W2K1057  
SERIAL NO: 09/931,144 / EXAMINER: NORRIS  
FILED: 08/16/2001 / ART UNIT: 2827  
TITLE: SOLDERABLE INJECTION-MOLDED INTEGRATED CIRCUIT  
SUBSTRATE AND METHOD THEREFOR

#4/A  
Andt  
Election  
J. Mcmillen

11/10/02

Assistant Commissioner  
for Patents  
Washington, D.C. 20231

Weiss & Moy, P.C.  
4204 North Brown Avenue  
Scottsdale, Arizona 85251-3989

October 29, 2002

I hereby certify that on the 29<sup>th</sup> day of October, 2002,  
this correspondence is being deposited with the U.S.  
Postal Service as first class mail in an envelope  
addressed to: Assistant Commissioner for Patents,  
Washington, D.C. 20231.

  
Jeffrey D. Moy

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TECHNOLOGY CENTER 2800

Dear Sir:

**AMENDMENT LETTER**

This is in response to the Office Action dated September 30,  
2002 in regards to the above identified patent application. Please  
amend the subject patent application as follows: